

A

B

C

D

E

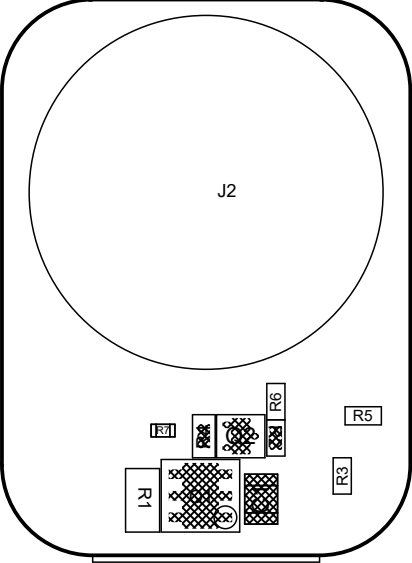
ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.
Assembly shall conform with RoHS Directive 2011/65/EU.
Components shall be placed according to the associated CPL and BOM documents.
Lead-free SAC305 solder shall be used.
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.
BGA components shall be 100% checked with x-ray for solder bridges after reflow.
Finished assemblies shall be removed from panel prior to delivery.

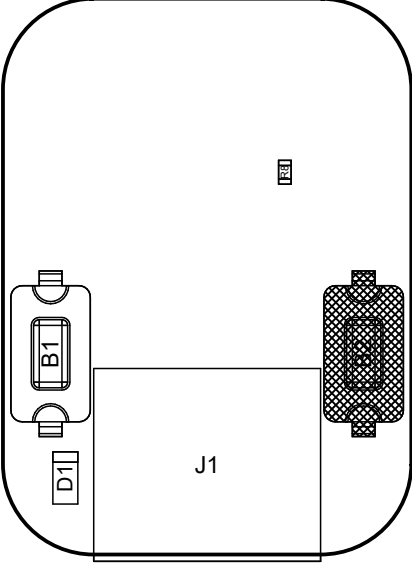
Notes:

- 1Note 1
- 2Note 2
- 3Note 3

View from Bottom side (Scale 3:1)



View from Top side (Scale 3:1)



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|---------------------------|----------------------|
| Title: NG6013 | |
| Number: | Revision: R3M2 E3 |
| Date: 03/08/2022 | Sheet: 1 of 1 |
| Drawn by: Nejic Gostincar | |



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